



1.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

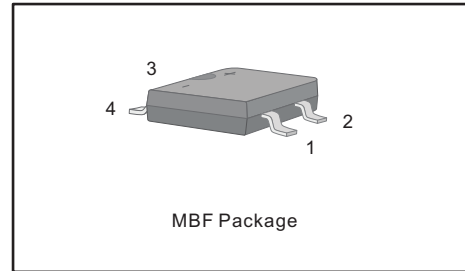
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 800 V
- Forward Current - 1.0 A
- Fast reverse recovery time
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMB1F-10	FMB2F-10	FMB4F-10	FMB6F-10	FMB8F-10	FMB10F-10	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^{\circ}\text{C}$	I_O	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Maximum Forward Voltage at 1.0 A	V_F	1.3						V
Maximum DC Reverse Current $T_a = 25\text{ }^{\circ}\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^{\circ}\text{C}$	I_R	5.0 50						μA
Typical Junction Capacitance (Note1)	C_j	15						pF
Maximum Reverse Recovery Time (Note2)	t_{rr} $t_{rr(TYP.)}$	500 300						ns
Typical Thermal Resistance (Note3)	$R_{\theta JA}$ $R_{\theta JC}$	80 25						$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	$-55 \sim +150$						$^{\circ}\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $t_{rr} = 0.25\text{ A}$.

3. Mounted on glass epoxy PC board with $4 \times 1.5 \times 1.5$ " (3.81 $\times$ 3.81 cm) copper pad.



Fig.1 Average Rectified Output Current Derating Curve

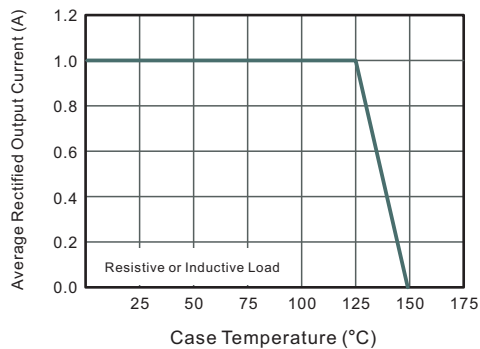


Fig.2 Typical Reverse Characteristics

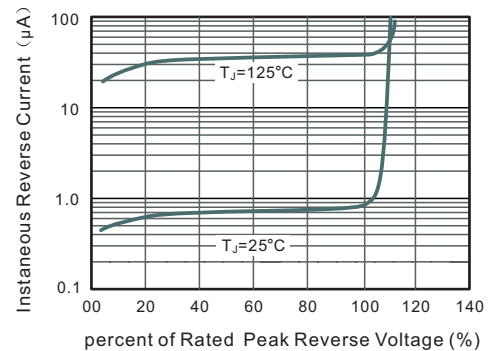


Fig.3 Typical Instantaneous Forward Characteristics

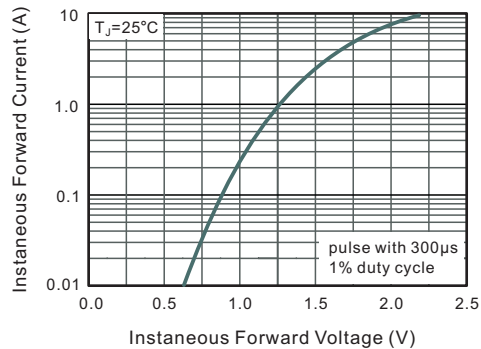


Fig.4 Typical Junction Capacitance

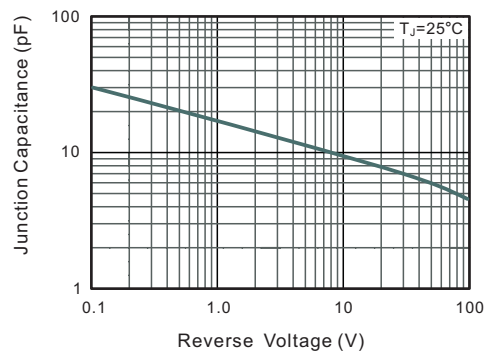
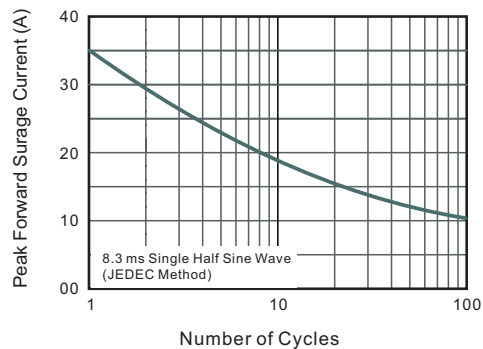


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

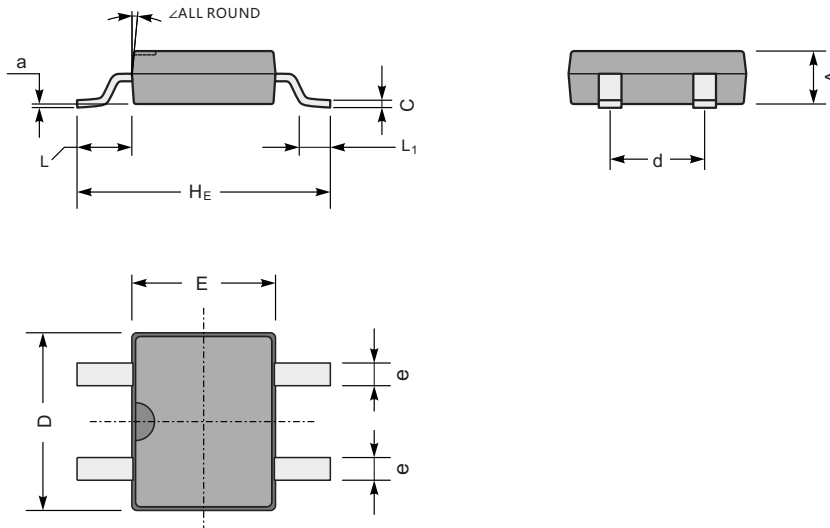




PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

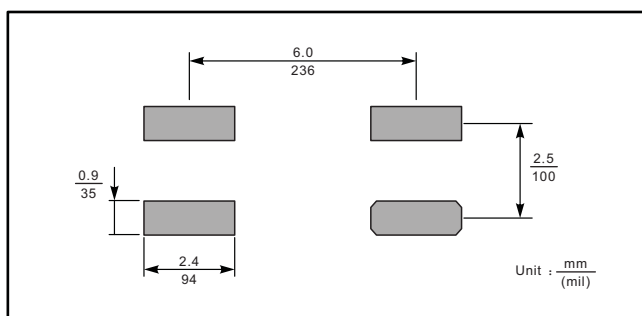
MBF



MBF mechanical data

UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.6	0.22	5.0	4.1	7.0	2.7	0.8	1.7	1.1	0.2	7°
	min	1.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	—	
mil	max	63	8.7	197	161	276	106	31	67	43	8	
	min	47	5.9	177	142	252	91	20	51	20	—	

The recommended mounting pad size



Marking

Type number	Marking code
FMB1F-10	F10M01
FMB2F-10	F10M02
FMB4F-10	F10M04
FMB6F-10	F10M06
FMB8F-10	F10M08
FMB10F-10	F10M10

